

PRIMERGY TX300 S8

PRIMERGY RX350 S8

System configurator and order-information guide

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Instructions

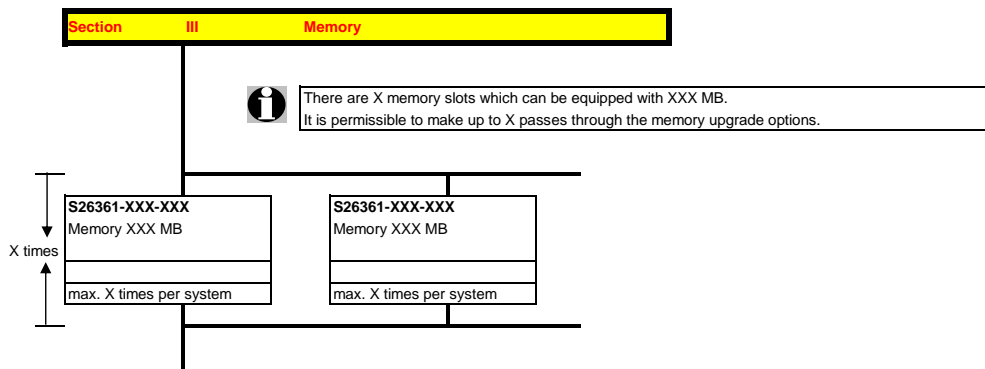
This document contains basic product and configuration information that will enable you to configure your system via PC-/SystemArchitect.

Only these tools will ensure a fast and proper configuration of your PRIMERGY server or your complete PRIMERGY Rack system.

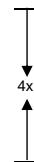
You can configure your individual PRIMERGY server in order to adjust your specific requirements.

The System configurator is divided into several chapters that are identical to the current price list and PC-/SystemArchitect.

Please follow the lines. If there is a junction, you can choose which way or component you would like to take. Go through the configurator by following the lines from the top to the bottom.



In one chapter you can only select as many components (here 4x) as the arrow indicates.



Please note that there are information symbols which indicate necessary information.



For further information see:

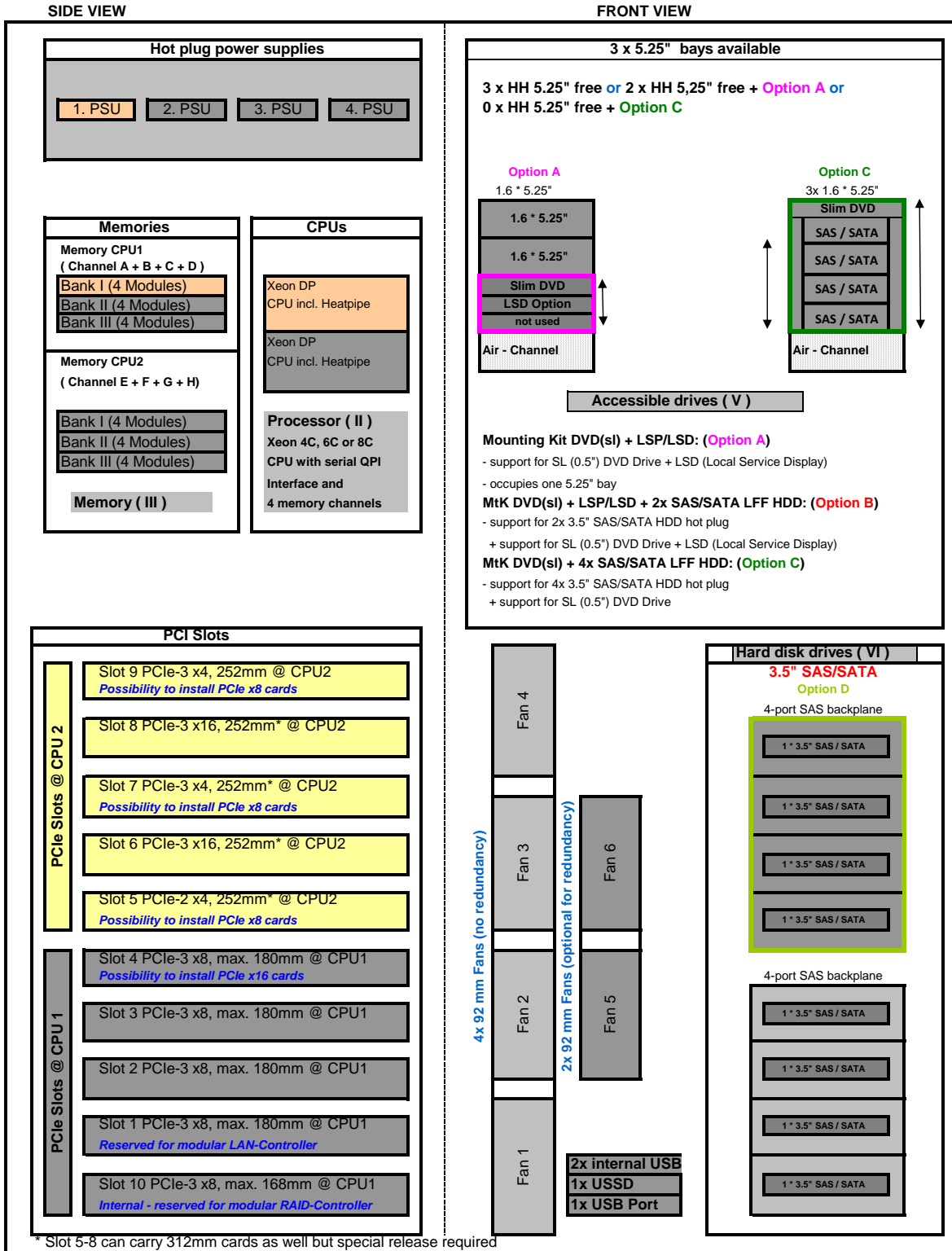
http://ts.fujitsu.com/products/standard_servers/index.html (internet)

https://partners.ts.fujitsu.com/com/order-supply/configurators/primergy_config/Pages/default.aspx (extranet)

Prices and availability see price list and PC-/SystemArchitect. Subject to change and errors excepted.

Configuration diagram PRIMERGY

System unit (3.5" HDDs)

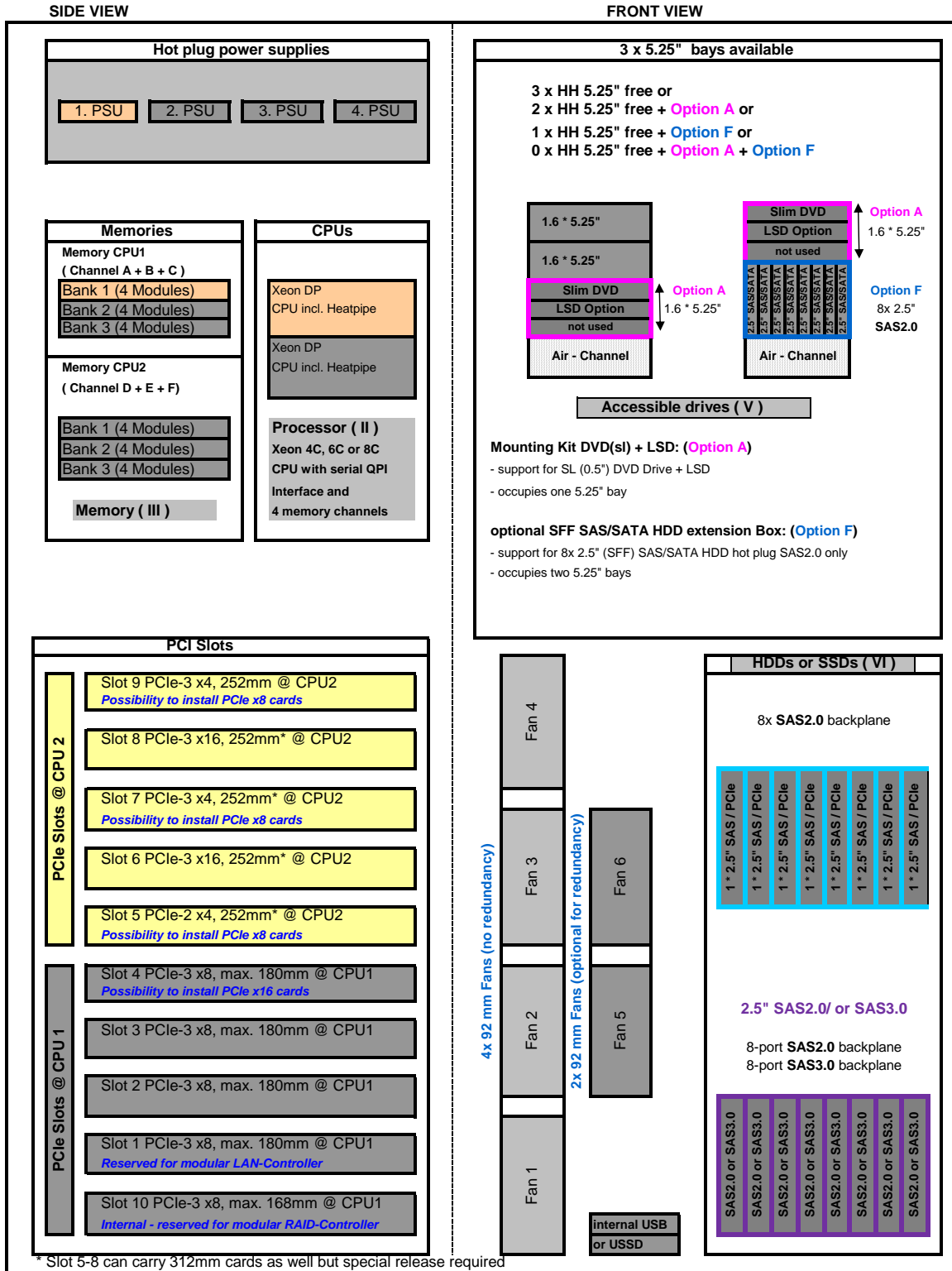


Key: Included in basic unit Option (LP ready = Slots for low profile boards)

One CPU, one memory per CPU and one PSU has to be selected for an orderable basic unit.

Configuration diagram PRIMERGY

System unit (2.5" HDDs) prepared for up to 8, 16 or 24x 2.5" Hard disk drives



Key: Included in basic unit Option (LP ready = Slots for low profile boards)

One CPU, one memory per CPU and one PSU has to be selected for an orderable basic unit.

Start PRIMERGY TX300 S8

Section I - base unit



SAS - System unit, Rack and Floorstand

lockable front bezel for floorstand version
 All Base units are equipped with
 - 4 Hot-Plug Power Supply Slots
 - 4 Standard Fans (92mm; redundancy requires 2 additional Fans)
 - SAS/ SATA backplane with hot plug bays only for 4x 3.5" HDDs (only LFF base units)
 - SFF base units do not contain backplanes (they need to be configured separately)
 Integrated ServerView Diagnostics Technology with an modul for indication of failed components via LEDs. The LEDs can be displayed during service even without mains connection.
 Simultaneously components which can be replaced by the customer are marked

Options:

- * up to 4 hot plug power supply modules with either 450W or 800W (no mix allowed)
- * Upgrade options for up to 12x 3.5" or 24x 2.5" HDDs
- * Optional modular RAID 0/1 controllers with IME (Integrated Mirroring Enhanced) support based on LSI 1064 or LSI SAS2008 chipset (ist das auf dem Board?) or optional modular RAID 5 controller based on LSI SAS2108 chipset.
- * up to 3 drive bays 5,25" for accessible drives (ODD, backup drives,...)
- * One LC- display for LocalView can be configured with an optional frame (occupies a slim bay)

Cables

- * SATA cable for DVD
- * 2x SAS cables for connection of 4 SAS-ports each incl. signaling

Software

- * ServerView Suite Software incl. ServerStart, ServerBooks, Management Software and Updates

Systemboard D2649-B based on Chipset Intel® C600 Series(codenamed Patsburg)

- > 2 serial QPlinks (Quick Path Interconnect)
- > Up to two Xeon EP2600 v2 series CPUs (Socket-R)

10 PCIe slots in total (with 2 CPU)

- > 5 PCI slots @ first CPU:
 - 4x PCIe-3 x8 (1x notched for x16 cards)
 - 1x PCIe-3 x8 (for modular RAID only)
- > 5 PCI slots @ second CPU:
 - 2x PCIe-3 x16
 - 2x PCIe-3 x4
 - 2x PCIe-2 x4

System RAM (DDR3-1066, 1333, 1600 & 1866 MHz)

- 2x12 memory slots for max. 1.536GB RAM DDR3 available
- 12 DIMMs per CPU (4 channels with 3 slots per channel)
- Possible max. configurations are:
 - 24x 64GB LRDIMM (eight rank modules) = 1536GB
 - 24x 16GB RDIMM (dual rank modules) = 384GB
 - 16x 4GB UDIMM (dual rank modules) = 64GB (on special release only)
- First Memory (one module) has to be selected for an orderable basic unit per CPU
- Memory upgrade is possible module wise
- Memory mirroring is supported with 2 identical modules in channel A+B CPU 1 or D+E CPU 2
- Rank sparing mode is supported with min. 2x 1R/2R or 1x 4R modules for RDIMM or LRDIMM
- SDDC (Chipkill) is supported for RDIMMs (except x8 organisation) and LRDIMMs.

LAN onboard

Dual Port 10/100/1000 x4 PCI Express Gigabit Ethernet Intel LAN controller Powerville on-board

System Management

iRMC S4 (integrated Remote Management Controller) on-board with dedicated 10/100/1000 Service LAN-port and integrated graphics controller.
 The Service LAN-port can be switched alternatively on standard Gbit LAN port 1

Graphics controller

Graphics Controller integrated in iRMC S4 (integrated Remote Management Controller):
 Supported graphical resolutions are:
 1600x1200x16bpp 60Hz, 1280x1024x16bpp 60Hz, 1024x768x32bpp 75Hz, 800x600x32bpp 85Hz,
 640x480x32bpp 85Hz.
 1280x1024x24bpp 60Hz only possible if local monitor or remote video redirection is off

Connectivity

Interfaces at rear - 1x RS-232-C (serial, 9 pin) for iRMC S4 or OS or shared - 1x RS-232-C (serial, 9 pin) - 1x VGA (15 pins) - 4x USB 2.0 (UHCI) with 480MBit/s, no USB wakeup - 2x LAN RJ45, 1x Service-LAN RJ45	Interfaces at front - 2x USB 2.0 (UHCI) with 480MBit/s, no USB wakeup - 1x Service-LAN RJ45 as an option Interfaces internal: - 2x internal USB connectors for backup devices - 1x USB 2.0 (UHCI) with 480MBit/s for dongle usage (no USB wakeup) - 1x USSD
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TX300 S8 Floorstand System
 with four hot plug fans (no redundancy)
 without CPU, Memory and PSU with:

LFF Base Unit	S26361-K1456-V101
- 4-port SAS 2.0 backplane for 4x 3.5" hot plug SAS or SATA HDs incl. cables for connection to the modular 8-port SAS controllers	
SFF Base Unit	S26361-K1456-V201
This base unit comes w/o backplane, please choose the appropriate one in the following steps.	

RX350 S8 Rack System
 without CPU, Memory and PSU
 with four hot plug fans (no redundancy)

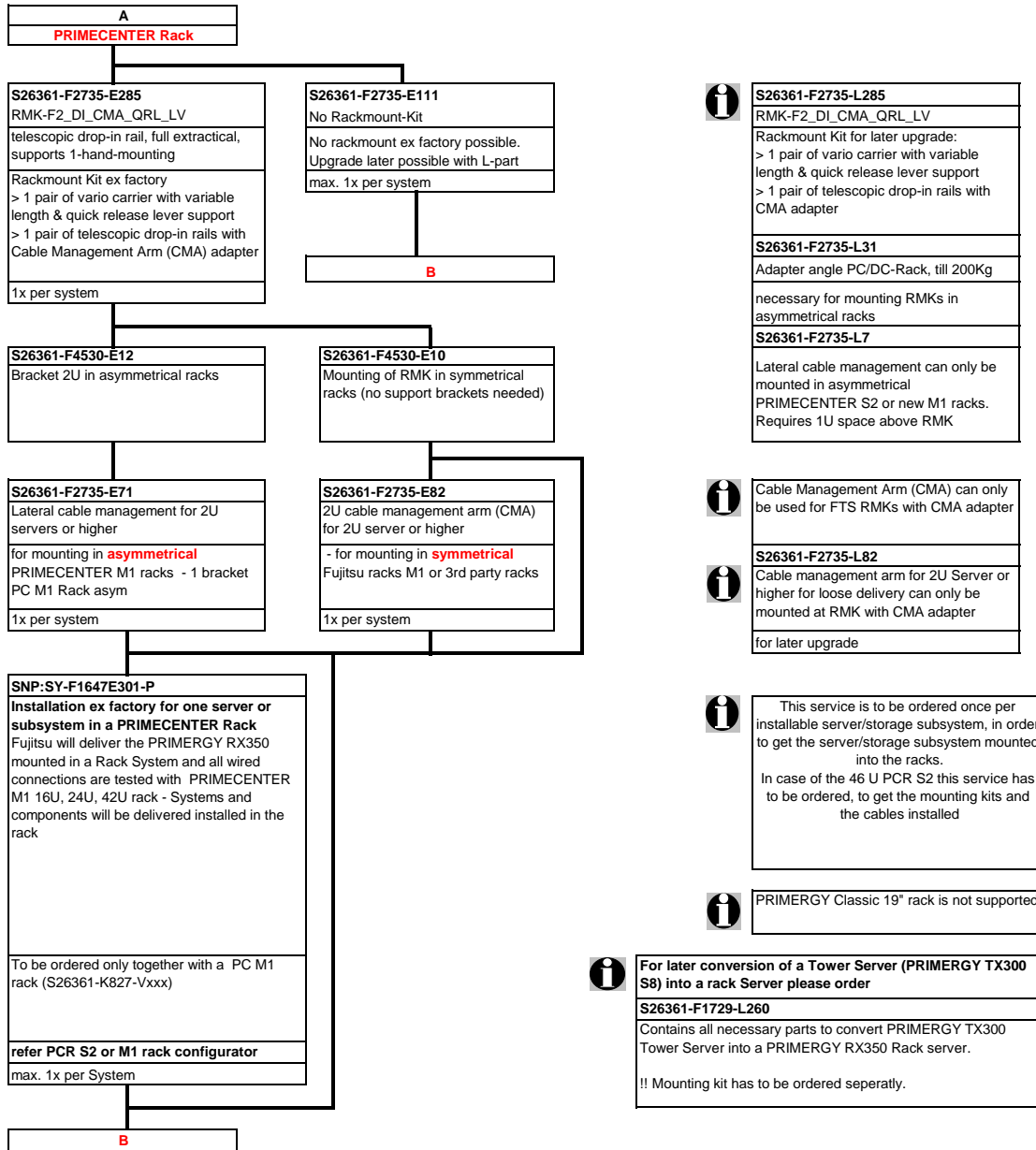
LFF Base Unit	S26361-K1456-V301
- 4-port SAS 2.0 backplane for 4x 3.5" hot plug SAS or SATA HDs incl. cables for connection to the modular 8-port SAS controllers	
SFF Base Unit	S26361-K1456-V401
This base unit comes w/o backplane, please choose the appropriate one in the following steps.	

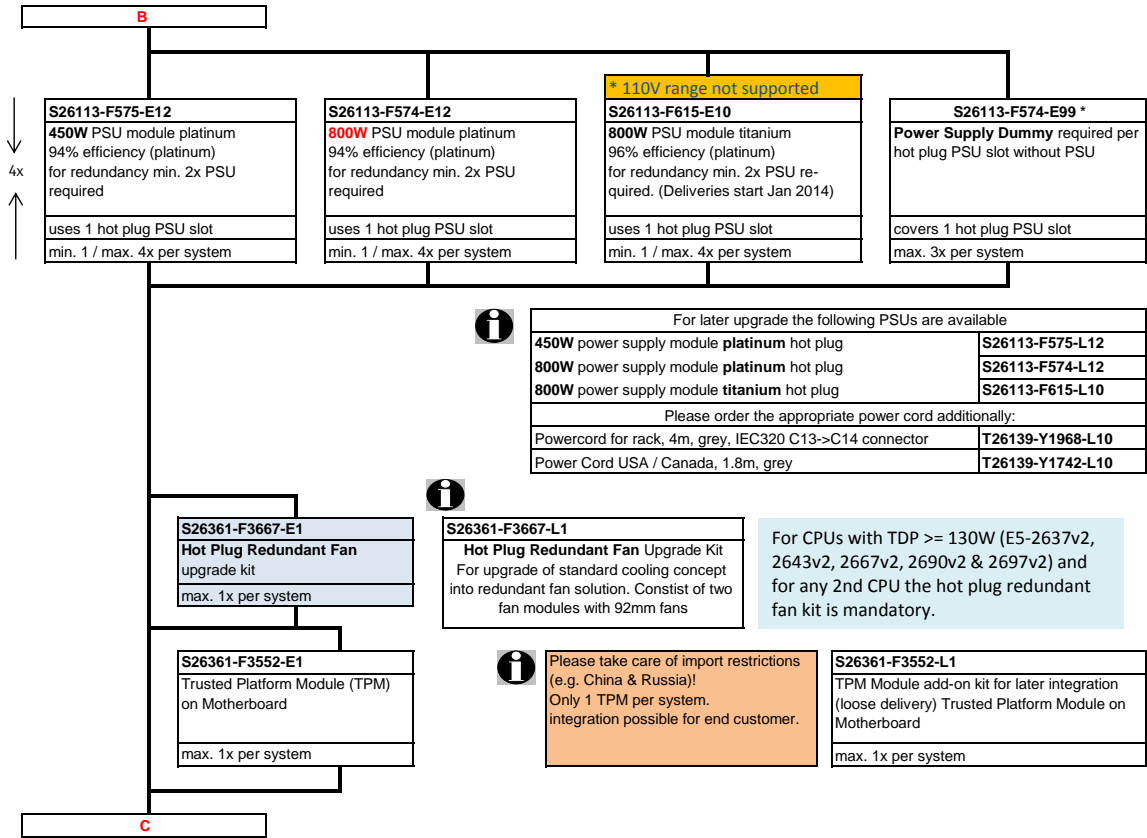
SX350 S8 Rack System
 without CPU, Memory and PSU
 with four hot plug fans (no redundancy)

LFF Base Unit	S26361-K1456-V903
- 4-port SAS 2.0 backplane for 4x 3.5" hot plug SAS or SATA HDs incl. cables for connection to the modular 8-port SAS controllers	
SFF Base Unit	S26361-K1456-V904
!without backplane! (please configure one of the "G" options)	

B

A





C

Section II Processor

PRIMERGY TX300/RX350 offers 2 processor sockets. Both PCIe-3 x16 slots are connected to CPU 2 and are useable with configured 2nd CPU only! Two processors with different clock frequencies are not possible. Please be aware, that a dual-processor system requires a multi-processor operating system.
.....
It is also possible to upgrade the TX300 with a second CPU later on. In this case don't forget to order a redundant fan kit as well.

Max. two CPUs can be selected per basic unit		
One of following CPUs has to be selected as first CPU for an orderable basic unit		
Optional second CPU has to be the same type like the first CPU		
Basic 4C CPUs		
- 1x 64-bit Intel Xeon (10MB Smart Cache) 1333 MHz DDR3 Bus; 6,40 GT/s QPI Bus and passive heat sink occupies socket for one CPU		
Xeon E5-2603v2 4C/4T 1.80GHz 10MB 6.40GT/s 1333MHz 80W		S26361-F3788-E180
Xeon E5-2609v2 4C/4T 2.50GHz 10MB 6.40GT/s 1333MHz 80W		S26361-F3788-E250
Standard Turbo 6C/8C CPUs		
- 1x 64-bit Intel Xeon (15/20MB Smart Cache); Hyper-Threading (HT); 1600 MHz DDR3 Bus; 7,20 GT/s QPI Bus and passive heat sink occupies socket for one CPU		
Xeon E5-2620v2 6C/12T 2.10GHz 15MB 7.20GT/s 1600MHz 80W		S26361-F3789-E210
Xeon E5-2630v2 6C/12T 2.60GHz 15MB 7.20GT/s 1600MHz 80W		S26361-F3789-E260
Xeon E5-2640v2 8C/16T 2.00GHz 20MB 7.20GT/s 1600MHz 95W		S26361-F3789-E200
Advanced Turbo+ 8C/10C CPUs		
- 1x 64-bit Intel Xeon (20/25MB Smart Cache); Hyper-Threading (HT); 1866 MHz DDR3 Bus; 8,00 GT/s QPI Bus and passive heat sink occupies socket for one CPU		
Xeon E5-2650v2 8C/16T 2.60GHz 20MB 8.00GT/s 1866MHz 95W		S26361-F3790-E260
Xeon E5-2660v2 10C/20T 2.20GHz 25MB 8.00GT/s 1866MHz 95W		S26361-F3790-E220
Xeon E5-2670v2 10C/20T 2.50GHz 25MB 8.00GT/s 1866MHz 115W		S26361-F3790-E250
Xeon E5-2680v2 10C/20T 2.80GHz 25MB 8.00GT/s 1866MHz 115W		S26361-F3790-E280
Xeon E5-2690v2 10C/20T 3.00GHz 25MB 8.00GT/s 1866MHz 130W		S26361-F3790-E300*
Segment Optimized CPUs		
- 1x 64-bit Intel Xeon (15/25/30MB Smart Cache); Hyper-Threading (HT); 1866 MHz DDR3 Bus; 8,00 GT/s QPI Bus and passive heat sink occupies socket for one CPU		
Xeon E5-2637v2 4C/8T 3.50GHz 15MB 8.00GT/s 1866MHz 130W		S26361-F3791-E350*
Xeon E5-2643v2 6C/12T 3.50GHz 25MB 8.00GT/s 1866MHz 130W		S26361-F3791-E330*
Xeon E5-2667v2 8C/16T 3.30GHz 25MB 8.00GT/s 1866MHz 130W		S26361-F3791-E300*
Xeon E5-2695v2 12C/24T 2.40GHz 30MB 8.00GT/s 1866MHz 115W		S26361-F3791-E240
Xeon E5-2697v2 12C/24T 2.70GHz 30MB 8.00GT/s 1866MHz 130W		S26361-F3791-E270*
Low Power 6C/10C CPUs		
- 1x 64-bit Intel Xeon (15/25MB Smart Cache); Hyper-Threading (HT); 1600 MHz DDR3 Bus; 7,20/8,00 GT/s QPI Bus and passive heat sink occupies socket for one CPU		
Xeon E5-2630L v2 6C/12T 2.40GHz 15MB 7.20GT/s 1600MHz 60W		S26361-F3792-E240
Xeon E5-2650L v2 10C/20T 1.70GHz 25MB 8.00GT/s 1600MHz 70W		S26361-F3792-E170

i Max. DDR3 Bus Speed depends on:
- max. DDR3 Bus Speed from the CPU and
- max. DDR3 Memory Speed and
- max. memory modules on one memory channel
For CPUs which do not offer 1866 MHz support, (Basic, Standard & Low Power class), System Architect will not offer memory modules supporting this frequency.

i *For CPUs with TDP = 130W (marked in blue and with * or for any 2nd CPU the hot plug redundant fan kit S26361-F3667-E1 is mandatory.

D

D

Section III -- Memory



- There are 12 memory slots per CPU for max.
 768GB LRDIMM (12x 64GB 8R)
 192GB RDIMM (12x 16GB 2R)
 64GB UDIMM (8x 8GB) on special Release only
 => max. 1.536GB for two CPUs (768GB per CPU), using LRDIMM

- The memory area is divided into 4 channels per CPU with 3 slots per channel
 - Slot 1 of each channel belongs to memory bank 1, the slot 2 belongs to memory bank 2, slot 3 belongs to memory bank 3

Registered, LR DIMMs and unbuffered memory modules can be selected
No mix of registered, load reduced and unbuffered modules allowed.
 Memory can be operated at 1.5V or 1.35V, even if the modules are of low voltage type.
 Memory operating voltage can be set within BIOS (1.5V is default setting for max. speed).
 In a single DIMM per channel configuration, following frequencies are supported:
 - 1.5V - 1866MHz max (depending on CPU)
 - 1.35V - 1600MHz max (depending on CPU, up to two LRDIMM per channel)
 - 1.35V - 1333MHz max (up to two UDIMM or RDIMM per channel)
 In a 3 DIMMs per channel configuration, memory will operate at 1.35V or 1.5V (no UDIMM allowed).
SDDC (Chipkill) is supported for registered / load reduced x4 organized memory modules only

1.) In the "Independent Channel Mode" is following configuration possible
 Channels can be populated in any order in Independent Channel Mode. All four channels may be populated in any order and have no matching requirements. All channels must run at the same interface frequency but individual channels may run at different DIMM timings (RAS latency, CAS latency, and so forth)
No mix of registered, load reduced and unbuffered modules allowed.

2.) "Rank Sparing Mode" configuration
 - Within a memory channel, one rank is a spare of the other ranks.
 The Spare Rank is held in reserve and is not available as system memory
 For the effective memory capacity, please refer to the spreadsheet below.
 The BIOS is set to the rank sparing setting.
Minimum configuration is: 2x 1R, 2x 2R or 1x4R DDR3 module per channel
This mode is not supported by unbuffered memory modules

3.) "Performance Mode" configuration
 - In this configuration, the memory module population ex factory is spread across all channels.
 The BIOS is set to the max. performance for memory.
Minimum configuration is: 4x identical modules per CPU

4.) In the "Mirrored Channel Mode" is following configuration possible
 - Each memory bank can optionally be equipped with 4x registered or load reduced or unbuffered DDR3 modules
In each memory bank channel A and B / C and D of CPU 1 or channel E and F / G and H of CPU 2 have to be equipped with identical modules for mirrored channel mode.
 In channel B / D is always the mirrored memory of channel A / B of CPU 1
 In channel F / H is always the mirrored memory of channel E / G of CPU 2
Minimum configuration is: 4x identical modules per CPU
This mode is not supported by unbuffered memory modules

E

E

S26361-F3694-E10 Independent Mode
 Independent Channel Mode allows all channels to be populated in any order. No specific Memory RAS features are defined
Requires min 1 memory Module per CPU

S26361-F3694-E1 Rank Sparing Mode Installation
 BIOS Setup factory preinstalled to this mode. One Rank is spare of other ranks on the same channel. Spare Rank is not shown in System Memory.
 For effective capacity within a channel, please have a look below.
Supported for RDIMM / LRDIMM only.
Requires min 2x 1R/2R or 1x 4R modules per CPU

S26361-F3694-E2 Performance Mode Installation
 BIOS Setup factory preinstalled for max. Performance, LV memory might be set to 1.5V operation. Four identical memory modules will be equipped in one memory bank to achieve highest memory performance. All four modules are active and full capacity can be used.
Multiple of 4 identical modules to be configured per CPU

S26361-F3694-E3 Mirrored Channel Mode Installation
 BIOS Setup factory preinstalled to this mode. Four identical memory modules are always equipped in one memory bank to use the Mirrored channel Mode. Only two modules contain active data, the remain two modules contain mirrored data
Supported for RDIMM / LRDIMM only.
Multiple of 4 identical modules to be configured per CPU

1x per CPU



Effective Memory capacity / Rank Sparing Mode, 1 Channel populated								
	RDIMM				LRDIMM			
	4GB 1R	8GB 1R	8GB 2R	16GB 2R	32GB 4R	64GB 8R		
1DPC	na	na	na	na	24GB	48GB		
2DPC	4GB	8GB	12GB	28GB	56GB	112GB		
3DPC	8GB	16GB	20GB	44GB	80GB	160GB		



Minimum one memory module or order code per CPU = first memory

8/12x per CPU, max.
2/3 modules per channel

Unbuffered Memory (UDIMM) no SDDC (chipkill) support
 - one DDR3 unbuffered ECC mem. Module, 1.35V
Choose up to 8 order codes per CPU
 8GB (1x8GB) 2Rx8 L DDR3-1600 U ECC S26361-F3807-E515 **special release only**

Registered Memory (RDIMM) with SDDC (chipkill) support
 - one DDR3 registered ECC mem. Module, 1.35V
 1333MHz supported with up to 2DPC (8 modules/CPU) and 1.35V
 1600MHz supported with up to 2DPC (8 modules/CPU) and 1.5V
Choose up to 12 order codes per CPU
 4GB (1x4GB) 1Rx4 L DDR3-1600 R ECC S26361-F3781-E514
 8GB (1x8GB) 1Rx4 L DDR3-1600 R ECC S26361-F3781-E515
 16GB (1x16GB) 2Rx4 L DDR3-1600 R ECC S26361-F3781-E516

Registered Memory (RDIMM) with SDDC (chipkill) support
 - one DDR3 registered ECC mem. Module, 1.5V
 1866MHz supported with up to 2DPC (8 modules/CPU)
Choose up to 12 order codes per CPU
 16GB (1x16GB) 2Rx4 DDR3-1866 R ECC S26361-F3793-E516

Registered Memory (RDIMM) no SDDC (chipkill) support
 - one DDR3 registered ECC mem. Module, 1.5V
 No mix with any other types of memory modules possible
 1866MHz supported with up to 2DPC (8 modules/CPU)
Choose up to 12 order codes per CPU
 8GB (1x8GB) 2Rx8 DDR3-1866 R ECC S26361-F3793-E515

Load Reduced Memory (LRDIMM) with SDDC (chipkill) support
 - one DDR3 load reduced ECC mem. Module, 1.35V
Choose up to 12 order codes per CPU
 32GB (1x32GB) 4Rx4 L DDR3-1600 LR ECC S26361-F3782-E517
 64GB (1x64GB) 8Rx4 L DDR3-1333 LR ECC S26361-F3783-E518

Load Reduced Memory (LRDIMM) with SDDC (chipkill) support
 - one DDR3 load reduced ECC mem. Module, 1.5V
 1866MHz supported with up to 2DPC (8 modules/CPU)
Choose up to 12 order codes per CPU
 32GB (1x32GB) 4Rx4 DDR3-1866 LR ECC S26361-F3848-E517

F



Note 1)
 Max. DDR3 memory speed depends on the memory configuration (No of mem modules per channel) as well as on the CPU type. The memory channel with the lowest speed defines the speed of all CPU channels in the system, also for the channels of the second CPU if configured. For real memory speed (depending on memory type / population), please check the spreadsheet "Memory speed" below



Note 2)
 Mix of memory modules is only possible within the same group

Memory Configuration PRIMERGY TX300 S8 / RX350 S8

Each CPU offers 12 Slots for DDR3 Memory Modules organised in 3 Banks and 4 Channels.

If you need more than 12 Slots you have to configure the 2nd CPU.

Depending on the amount of memory configured you can decide between 4 basic modes of operation (see explanation below).

There are 3 different kinds of DDR3 Memory Modules available: UDIMM / RDIMM and LRDIMM

UDIMM / RDIMM / LRDIMM offer different functionality. Mix of UDIMM / RDIMM / LRDIMM is not allowed.

If 1.5V and 1.35V DIMMs are mixed, the DIMMs will run at 1.5V

Mode	Configuration	UDIMM	RDIMM	RDIMM LRDIMM	Application
		x8	x8	x4	
SDDC (chipkill) support	any	no	no	yes	detect multi-bit errors
Independant Channel Mode	1, 2 or 3 Modules per Bank	yes	yes	yes	offers max. flexibility, upgradeability, capacity
Mirrored Channel Mode *)	4 identical Modules / Bank	no	no	yes	offers maximum security
Performance Mode	4 identical Modules / Bank	yes	yes	yes	offers maximum performance and capacity
Rank Sparing Mode *)	min. 2 Ranks / Channel	no	no	yes	balances security and capacity

*) For the delivery ex works the system will be prepared with dedicated BIOS setting.

Capacity	Configuration	UDIMM	RDIMM	LRDIMM	Notes
Min. Memory per CPU	1 Module / CPU	1x4GB	1x4GB	1x32GB	with one CPU
Max. Memory per CPU	8/12 Modules / CPU	8x4GB	12x16GB	12x64GB	with one CPU
Max. Memory per System	16/24 Modules / System	64GB	384GB	1536GB	if second CPU is configured

Memory-Speed:

Max. DDR3 memory speed depends on the memory configuration on one memory channel and the speed of the CPU

The memory channel with the lowest speed defines the speed of all CPU channels in the system

Mem. Speed provided by CPU	Real maximum memory-bus speed depending on CPU type, memory configuration (DPC) and voltage setting (BIOS)																	
	UDIMM 1866MHz						RDIMM 1866MHz						LRDIMM 4R 1866MHz					
	1.5V [default]			1.35V			1.5V [default]			1.35V			1.5V [default]			1.35V		
Voltage setting (BIOS)	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3	1	2	3
	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC	DPC
CPU with 1866MHz DDR3 Bus	1866	1600	-	1333	1333	-	1866	1866	1066	1333	1333	800	1866	1866	1066	1600	1600	1066
CPU with 1600MHz DDR3 Bus	1600	1600	-	1333	1333	-	1600	1600	1066	1333	1333	800	1600	1600	1066	1600	1600	1066
CPU with 1333MHz DDR3 Bus	1333	1333	-	1333	1333	-	1333	1333	1066	1333	1333	800	1333	1333	1066	1333	1333	1066

1R - Single Rank 4R - Quad Rank
 2R - Dual Rank 8R - Eight Rank

1DPC = 1 DIMM per Channel
 2DPC = 2 DIMM per Channel
 3DPC = 3 DIMM per Channel

Configuration hints:

- The memory sockets on the systemboard offer a color coding:

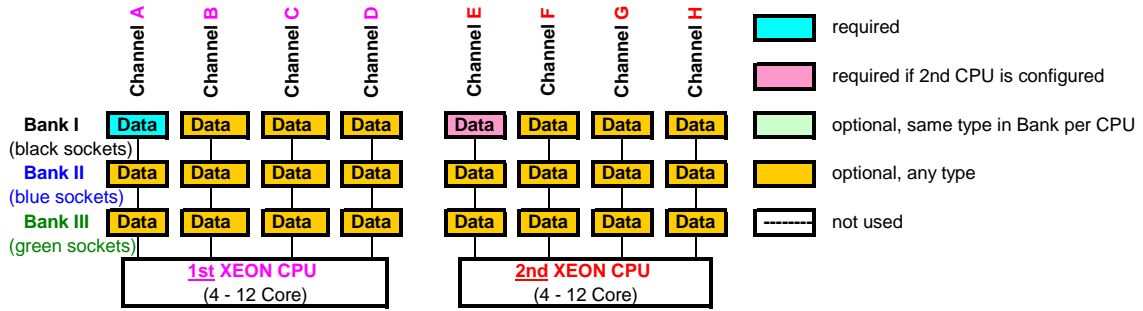
- Bank I** black sockets
- Bank II** blue sockets
- Bank III** green sockets

- A so called Bank consists of 1 memory module on every Channel available on one CPU (examples see below)

- Bank I on CPU 1/2** up to 4 memory modules connected to Channel A - H on the 1st/2nd CPU
- Bank II on CPU 1/2** up to 4 memory modules connected to Channel A - E on the 1st/2nd CPU
- Bank III on CPU 1/2** up to 4 memory modules connected to Channel A - E on the 1st/2nd CPU (can not be populated by UDIMM or 4R RDIMM memory modules)

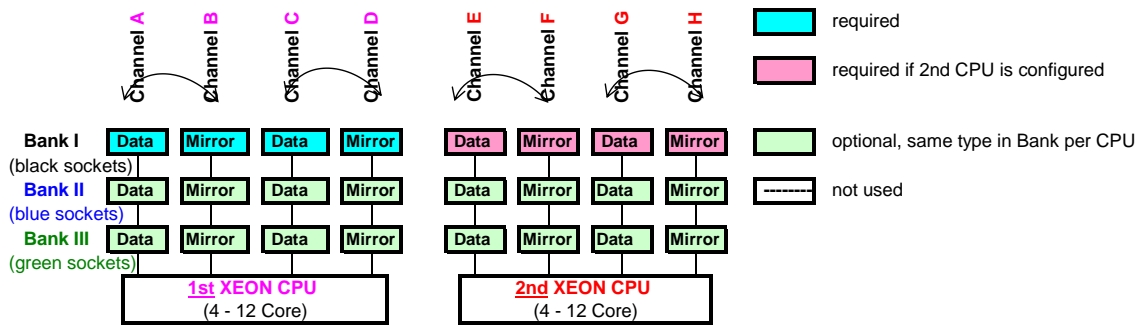
- See below and next page for a detailed descriptions of the memory configuration supported.

1. Independent Channel Mode



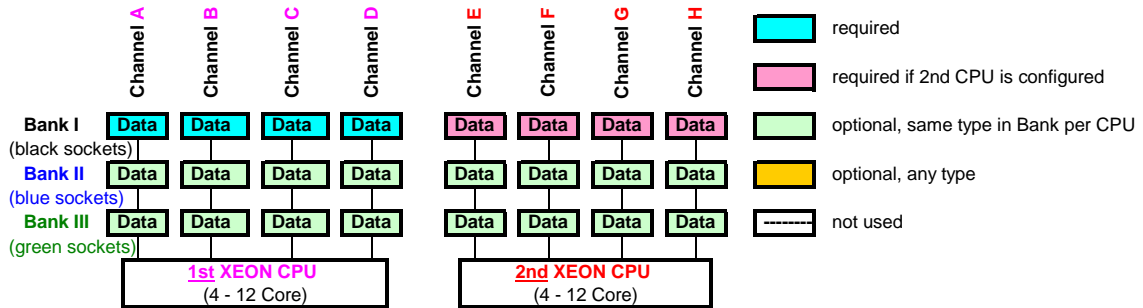
Independent Channel Mode allows all channels to be populated in any order
 Can run with differently rated DIMMs and use the settings of the slowest DIMM installed in the system

2. Mirrored Channel Mode



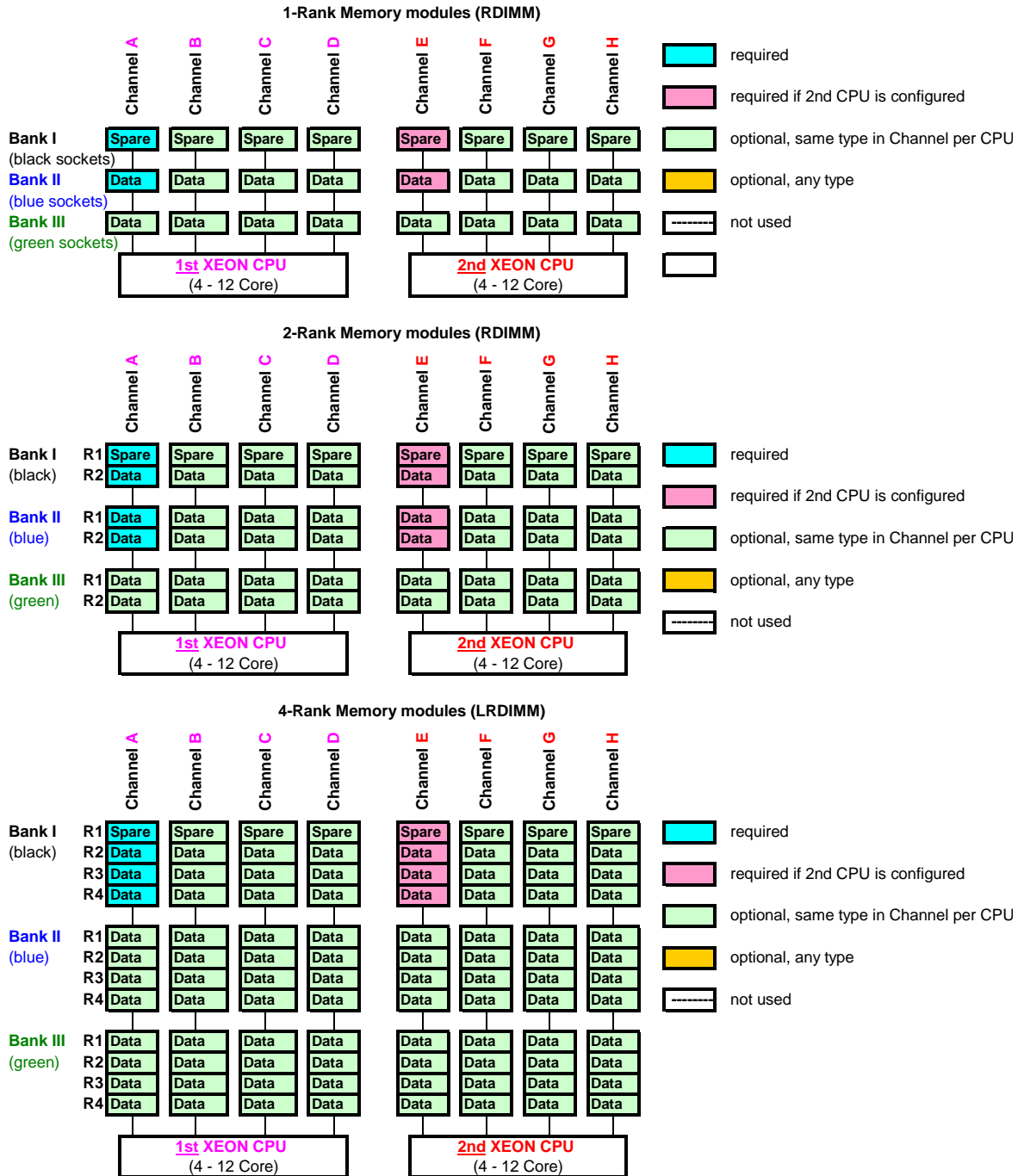
Mirrored Channel Mode requires identical modules on channel A,B, C, D (1st CPU) or channel E, F, G and H (2nd CPU)
 50% of the capacity is used for the mirror => the available memory for applications is only half of the installed memory
 If this mode is used, a multiple of 4 identical modules has to be ordered.

3. Performance Channel Mode

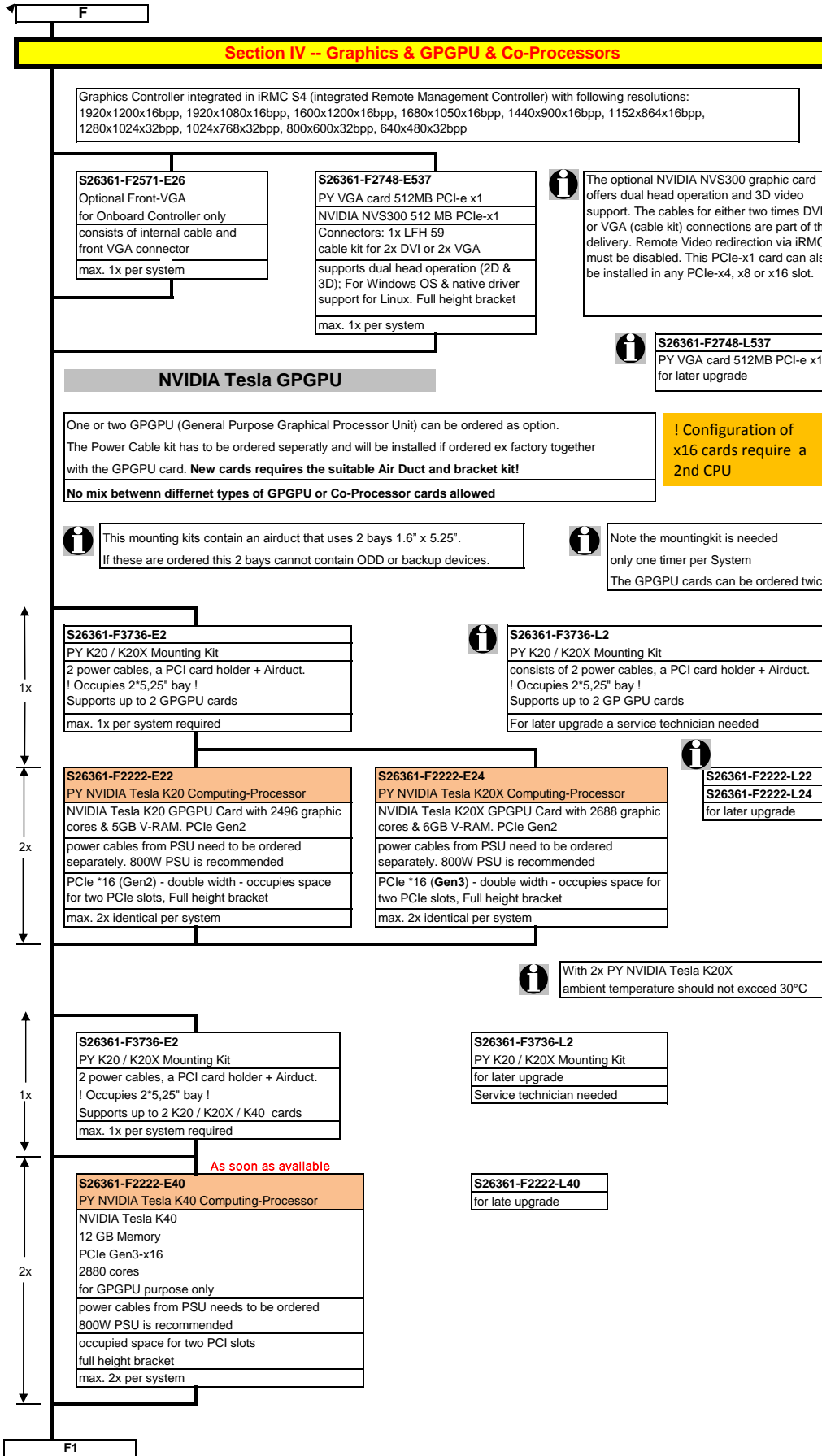


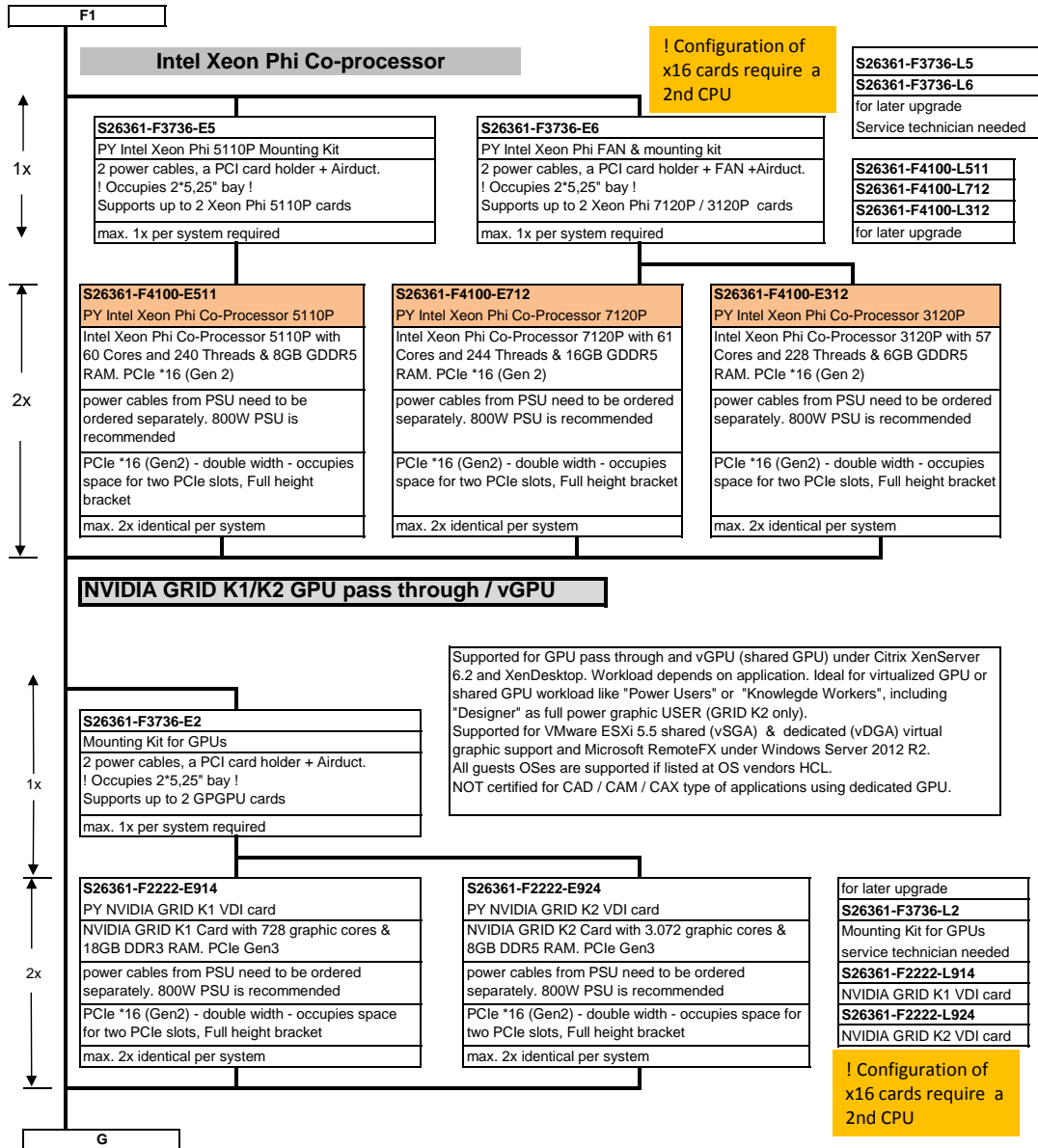
Performance Channel Mode requires identical modules on all channels of each Bank per CPU.
 If this mode is used, a multiple of 4 identical modules has to be ordered.

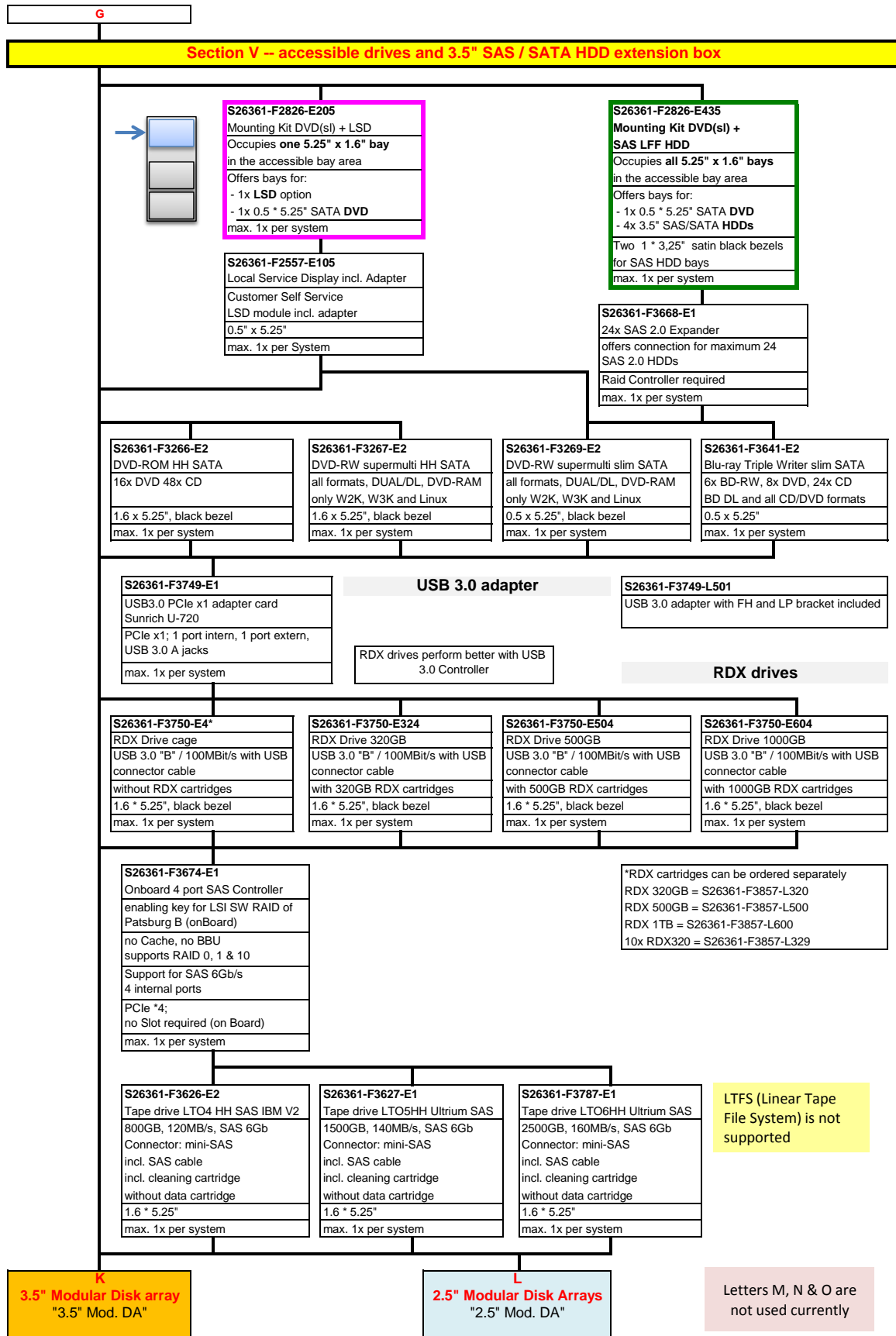
4. Rank Sparing Mode

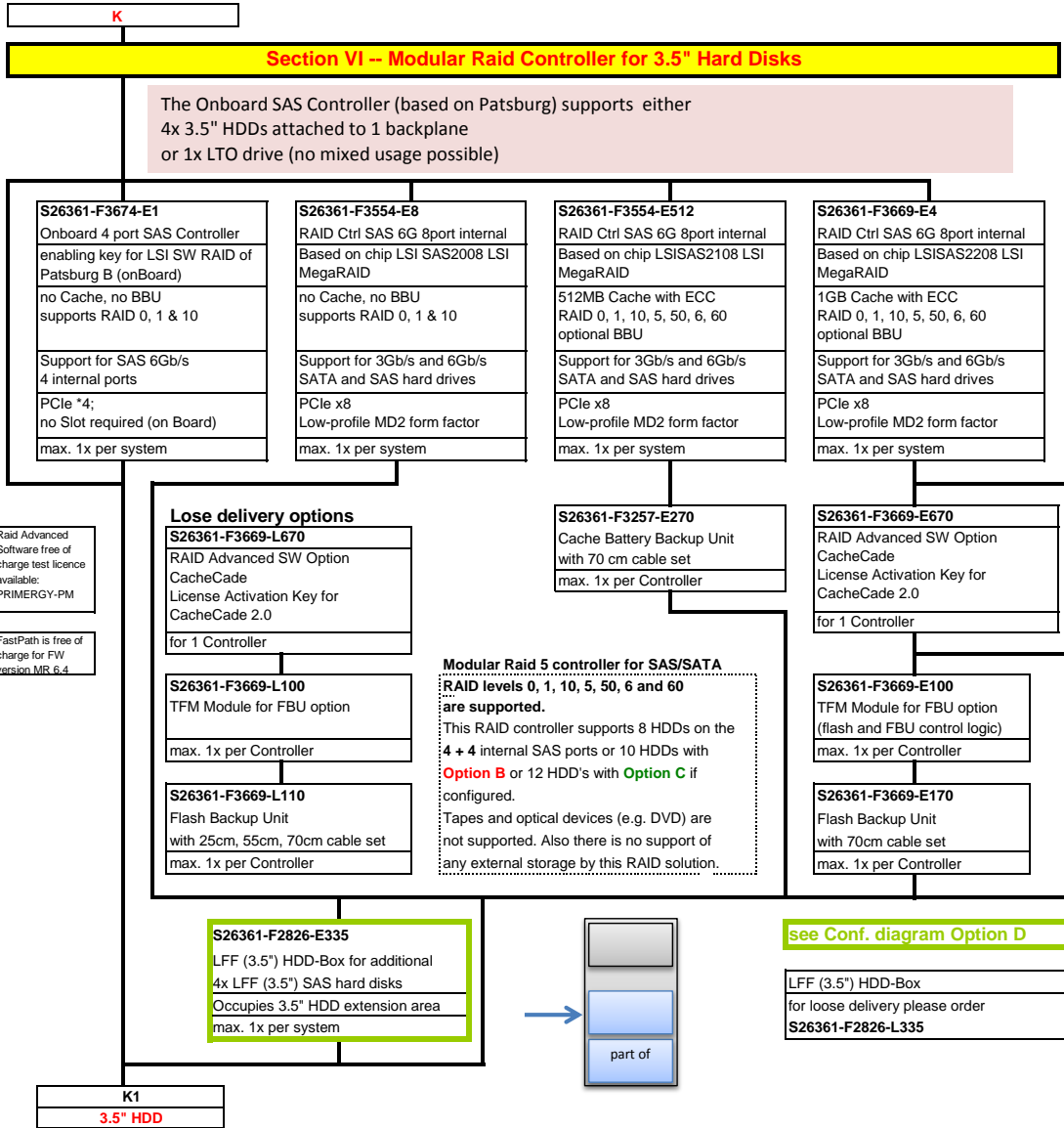


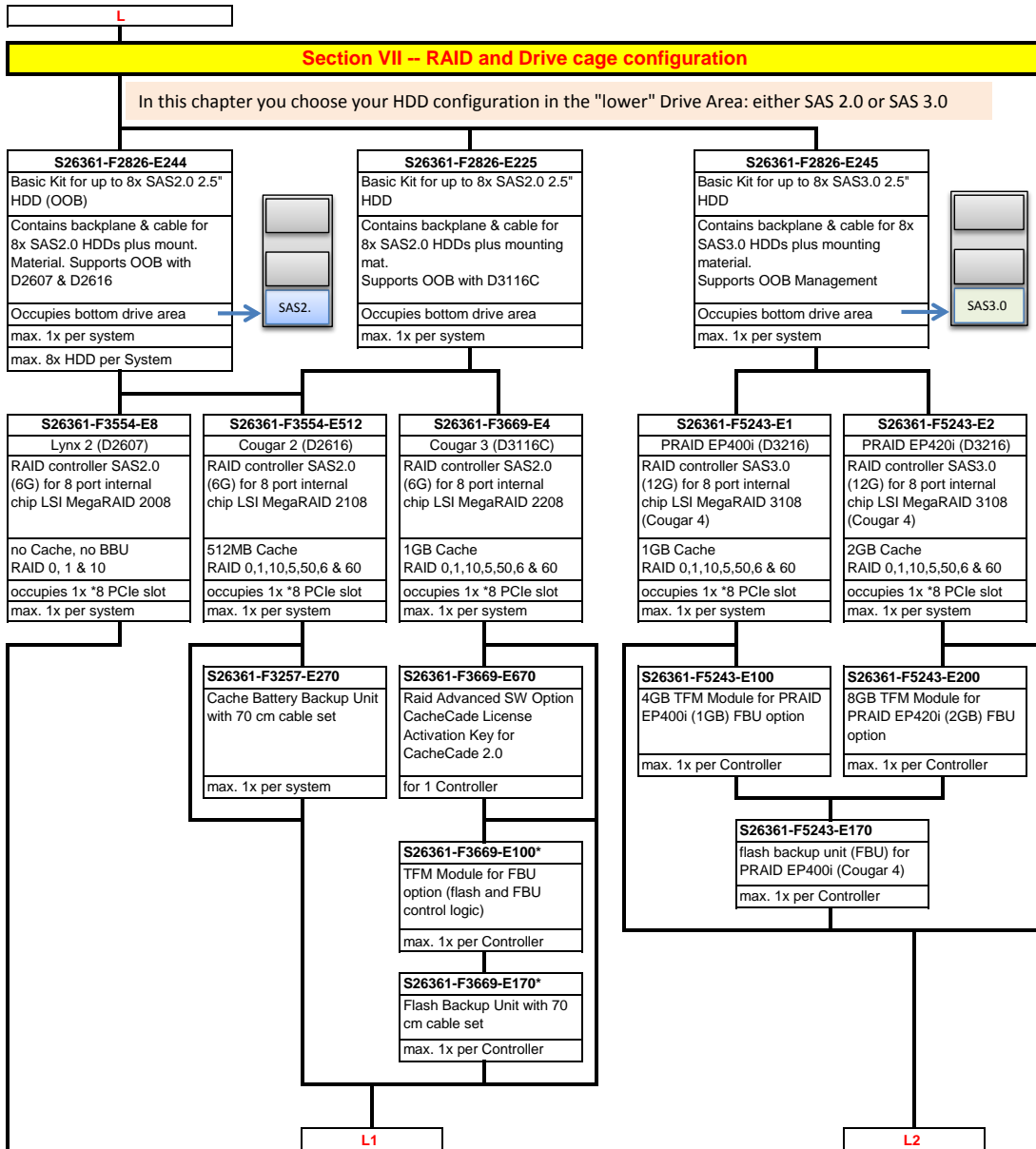
Rank Sparing Mode requires identical modules (same capacity and technology) within the same channel. The available memory for applications will vary depending on configuration. Please refer to the spreadsheet above "Effective Memory capacity with active Rank Sparing Mode". Population rule for Rank sparing mode is to achieve max. available memory, e.g. 6 DIMMs will be spread across two channels, each with 3DPC

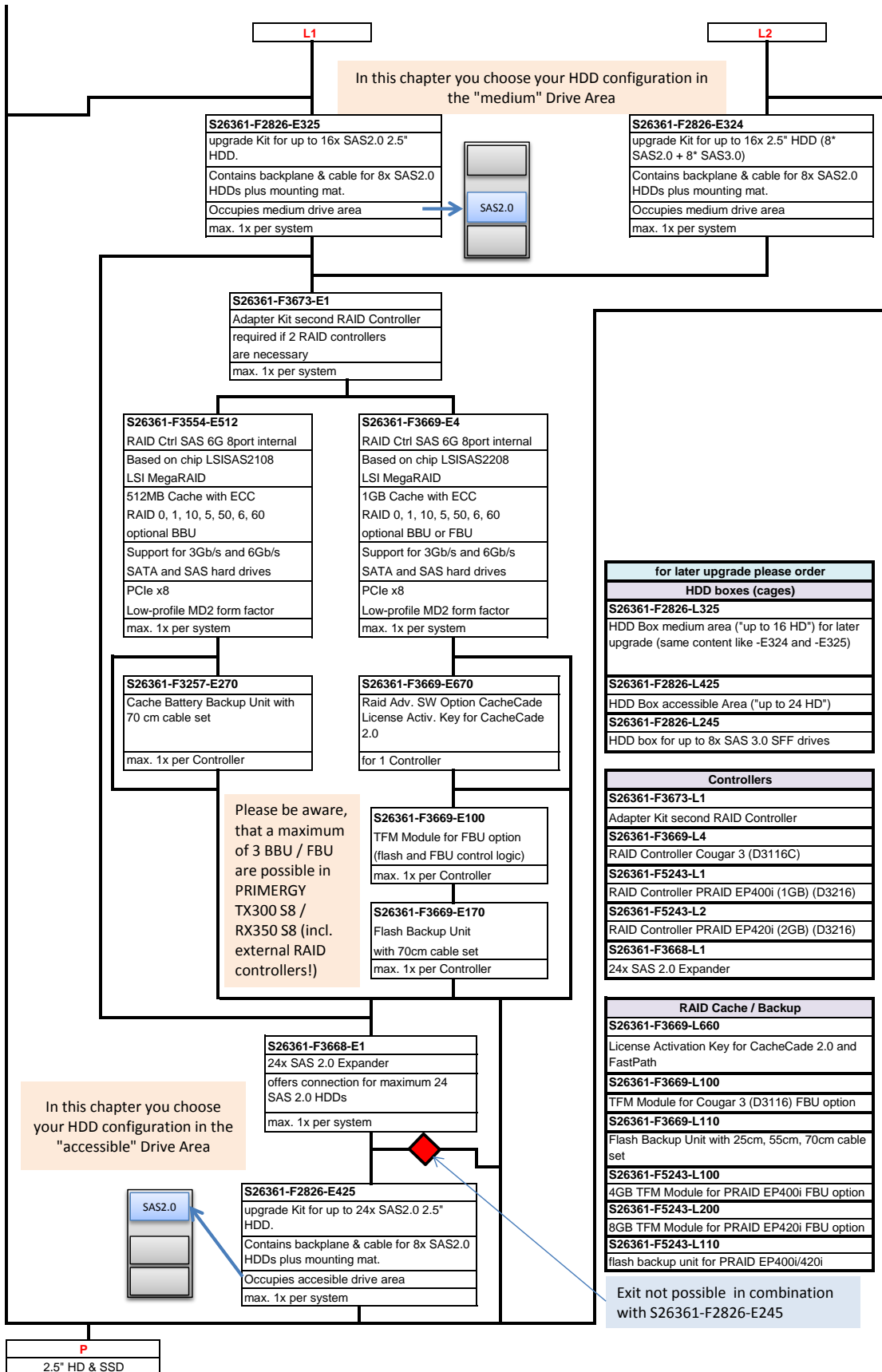


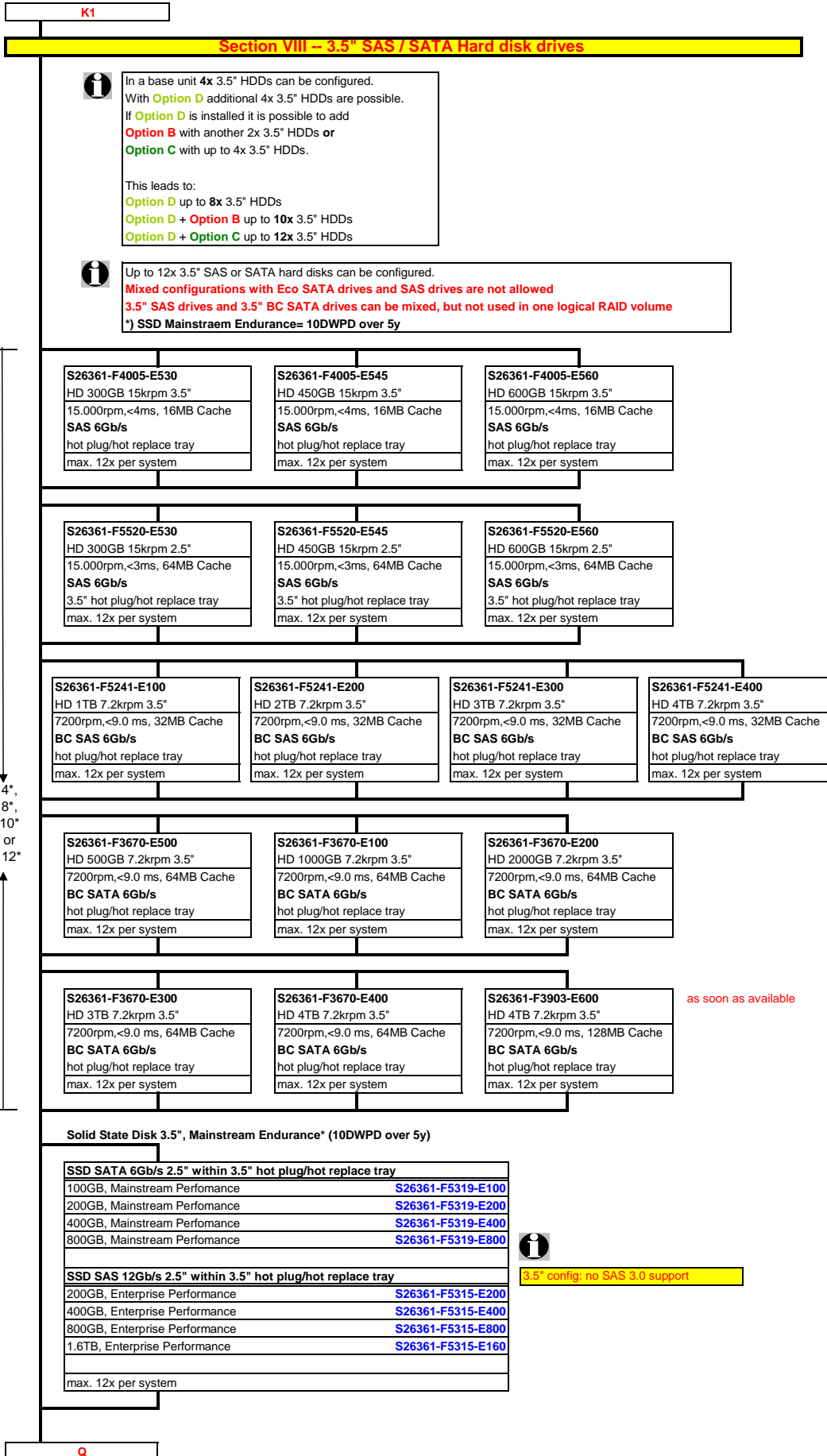


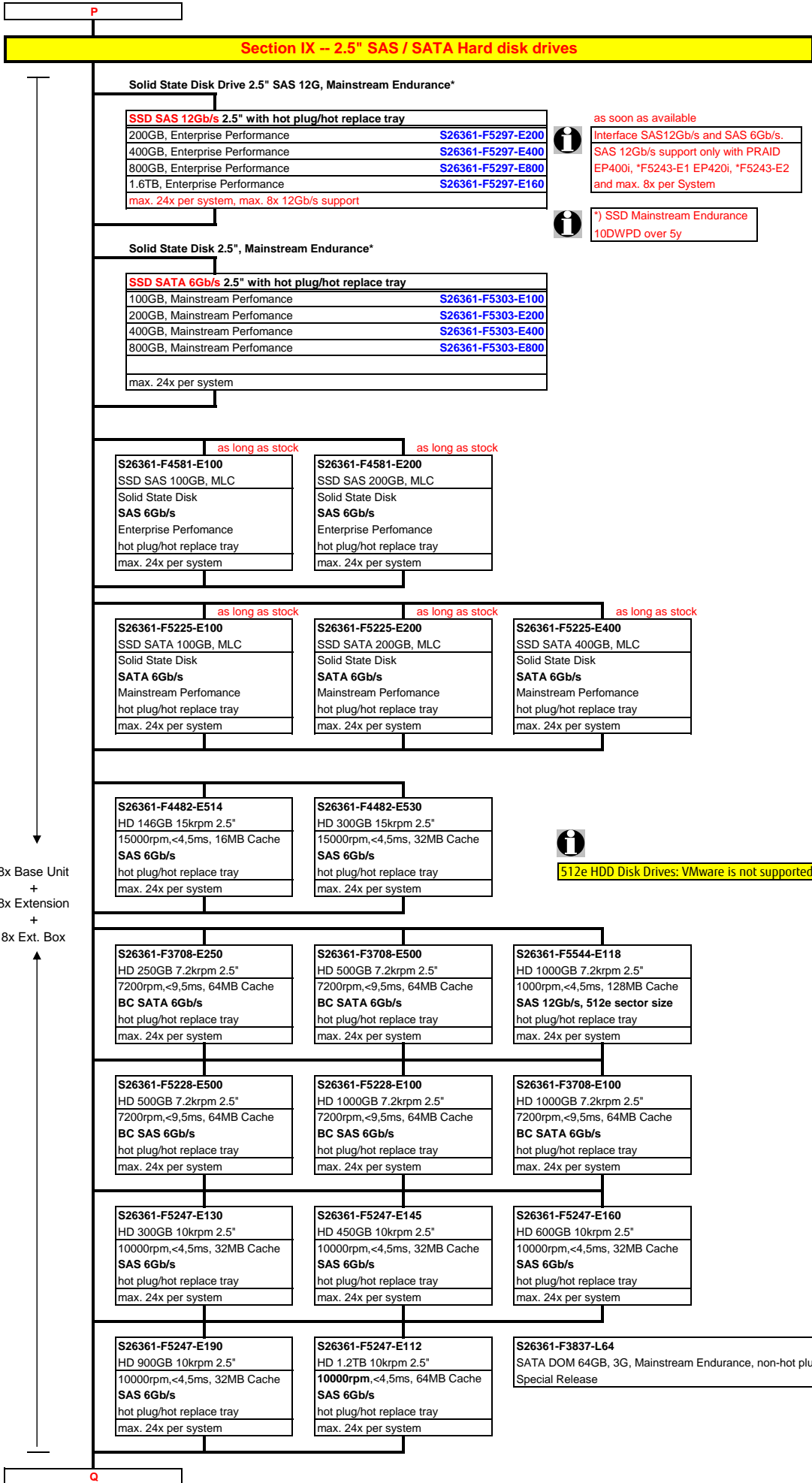


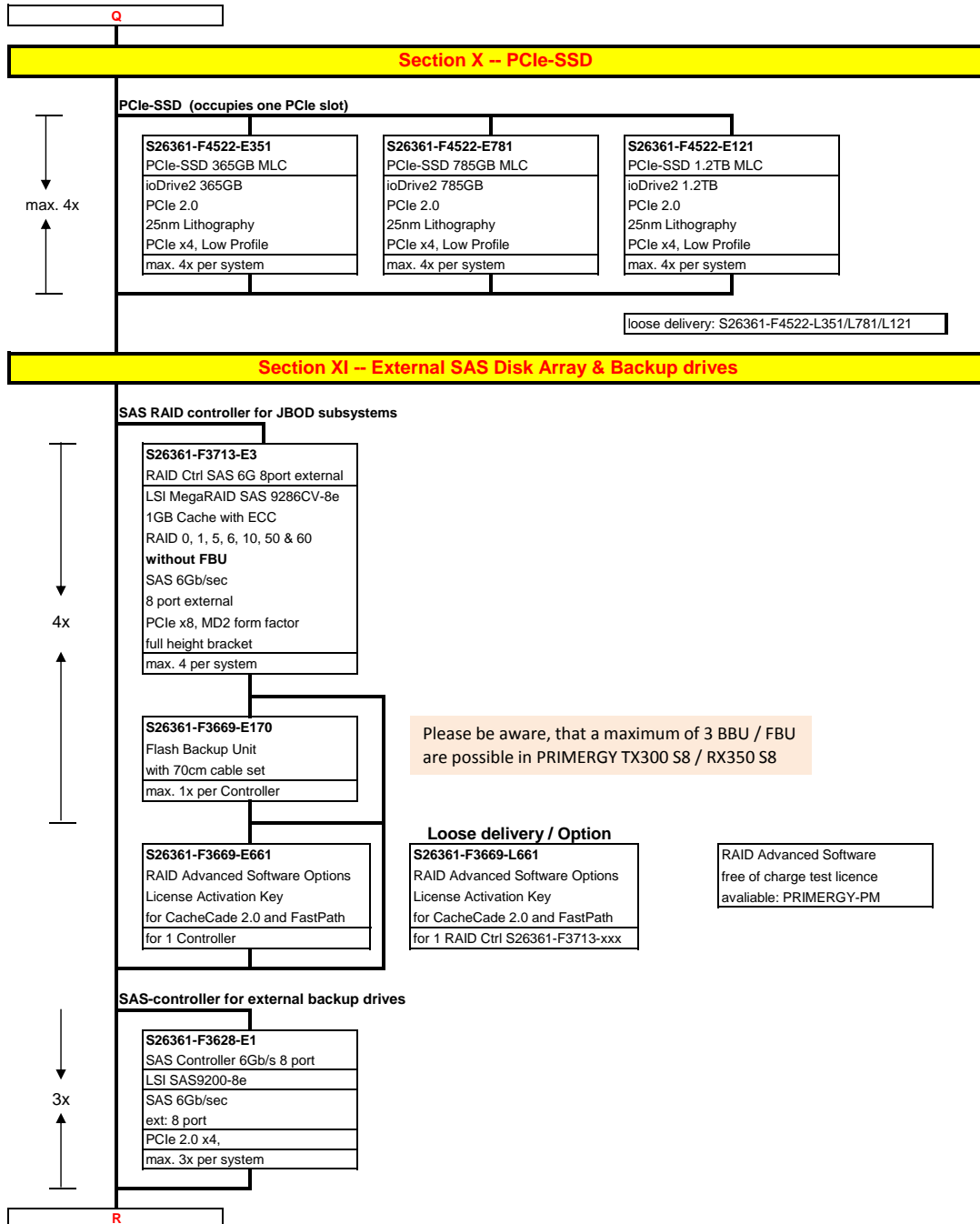


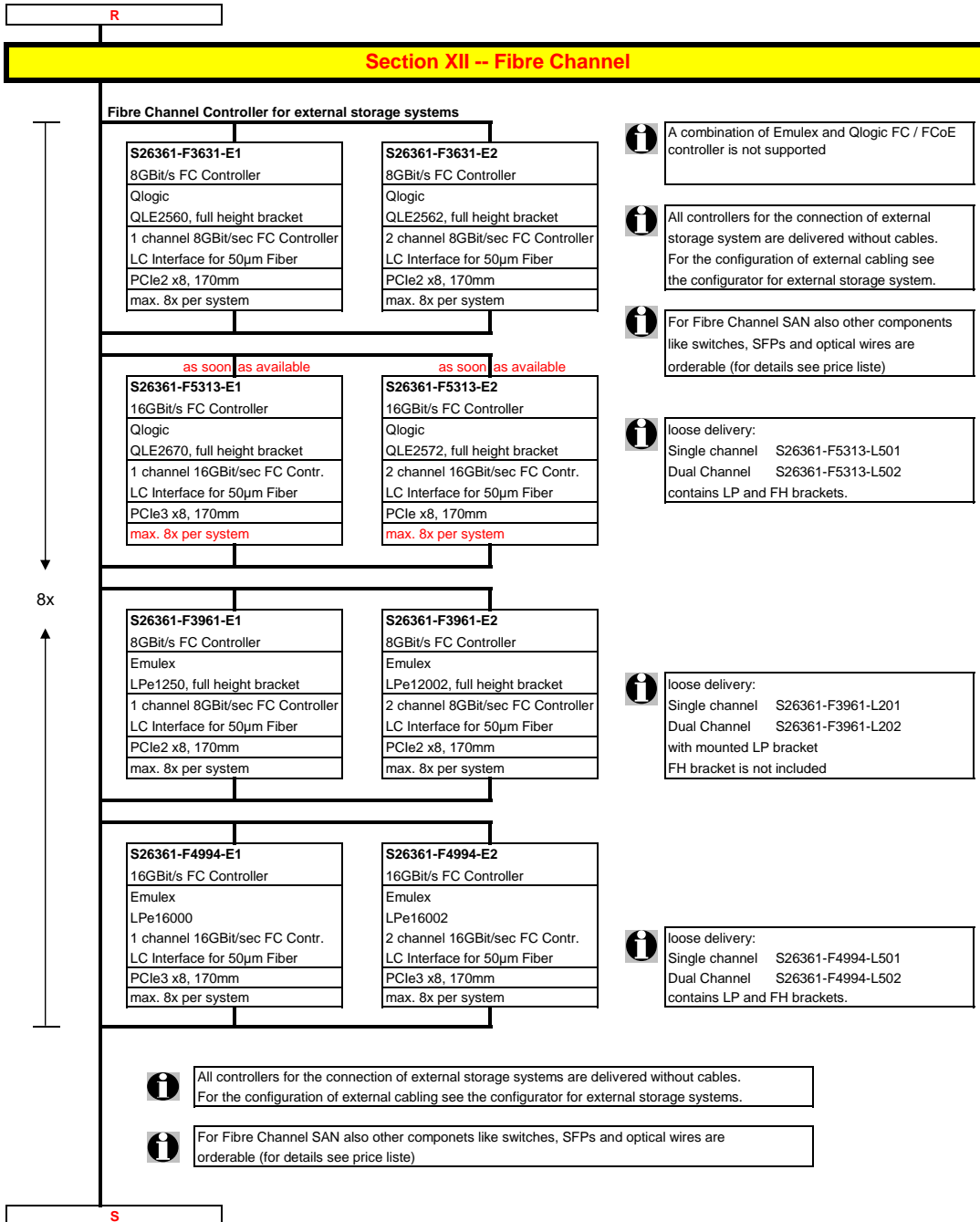


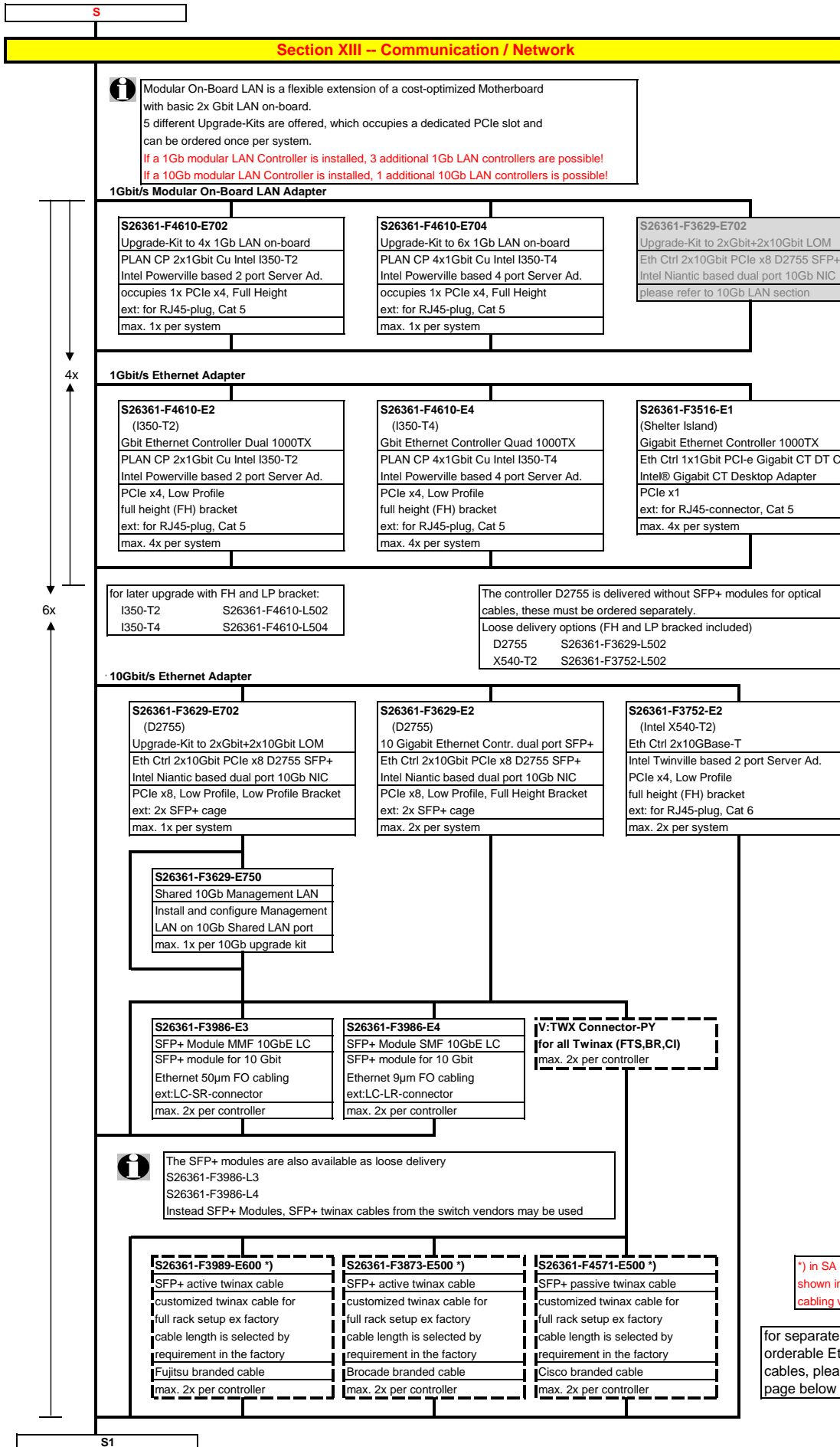


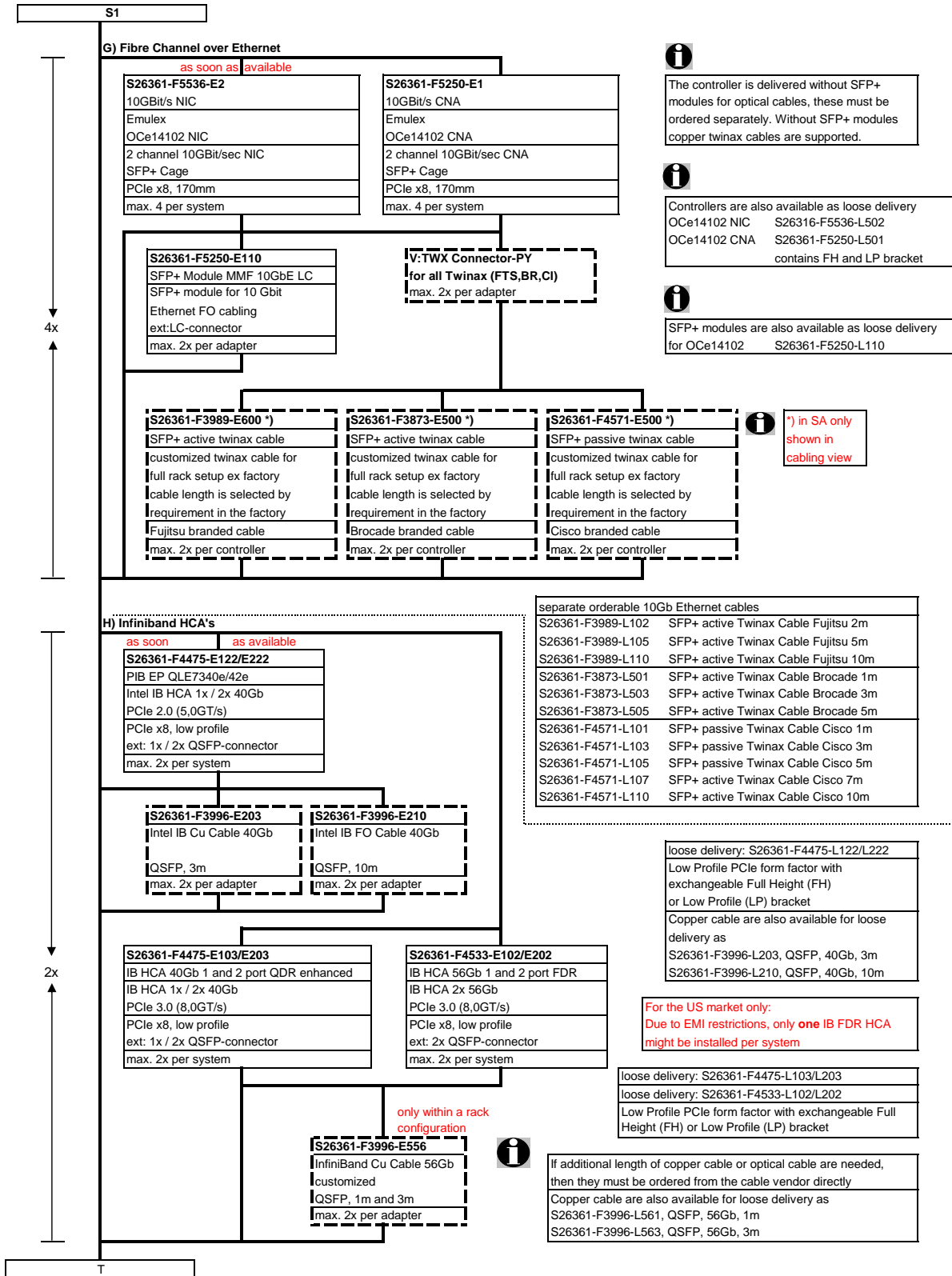


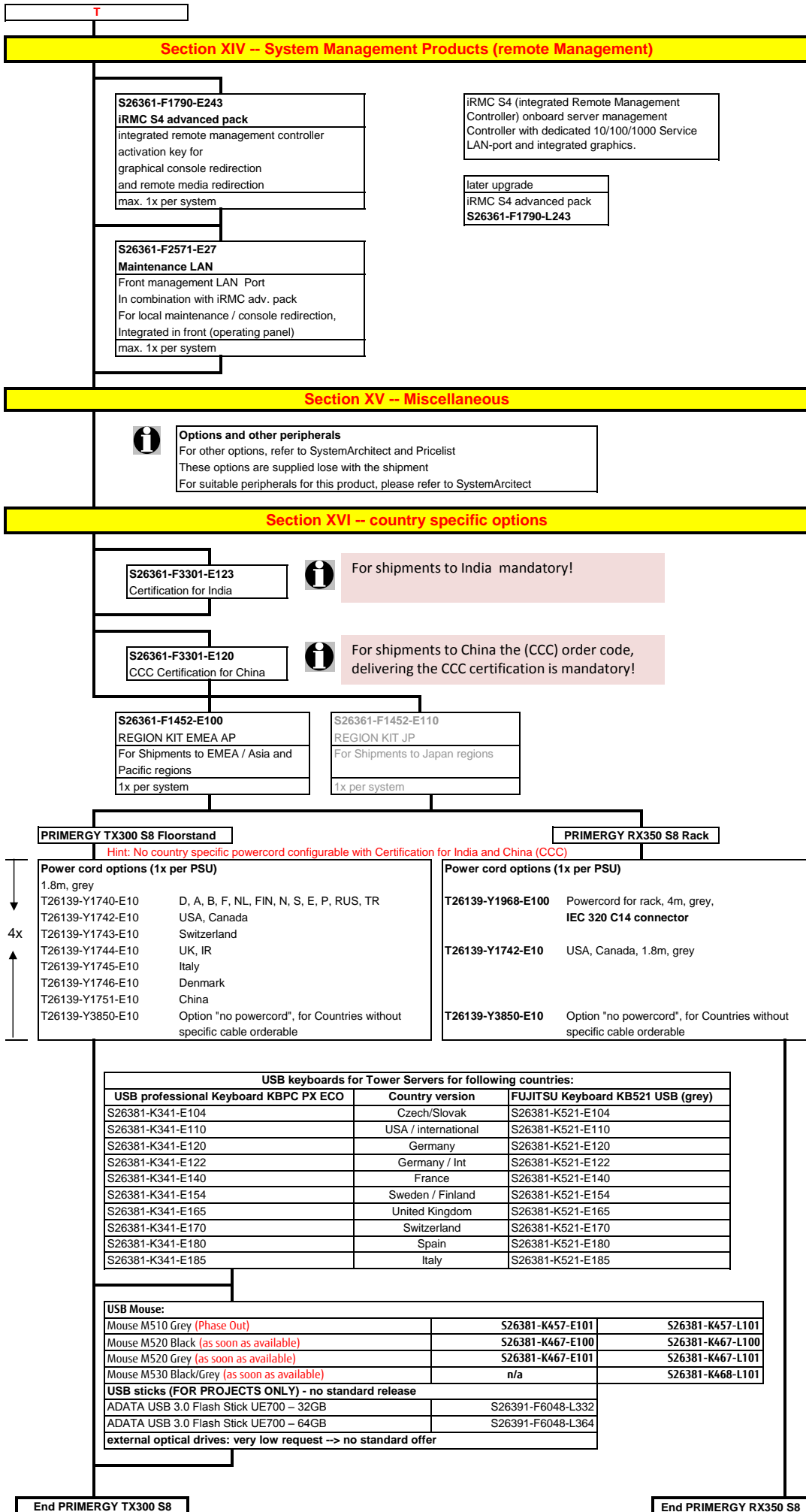












End PRIMERGY TX300 S8

End PRIMERGY RX350 S8

Change Report

Date	Order number/section	Changes
2015-10-27	USB mouse portfolio	USB mouse order codes updated
2015-07-01	S26361-F5243-x	Corrected Typos for PRAID EP400i and PRAID EP420i (EP was missing)
2015-06-11	T26139-Y1751-E10	China cabel added and country specific power cords added
2015-02-27	S26361-F5520-E*	Added 2.5" SAS 6G 15K HDD up to 600GB within 3.5" Carrier
2015-02-17	S26361-F3903-E600	Added HD SATA 6G 6TB 7.2K 512e HOT PL 3.5" BC
2015-01-27	Acc drives & HDD box	S26361-F2826-E105 deleted
2014-12-22		Explanation Text for GRID cards changed / reworked
2014-11-03	Conf.diagram 2.5" HDD	hints for PCIe SSD removed
2014-10-20	S26361-F5536-E2	added Emulex OCe14012 dual channel 10Gb NIC
2014-09-01	GFX/FC	limitation "Emulex / Xeon Phi" only in UEFI mode is deleted
2014-08-25	GFX	all x16 Cards require a 2nd CPU
2014-08-04	S26361-F5313-xxx	16Gb Qlogic added
2014-07-30	Keyboards, USB devices	K520 are EoL --> new KB K521; USB devices added
2014-07-28	S26361-F2826-E244	corrected: OOB S26361-F2826-E244 - only for up to 8x HDD
2014-07-22	Link to configurator	corrected on folder "instructions"
2014-07-10	S26361-F3787-E1	LTO6 drive: LTFS (Linear Tape File System) is not supported
2014-07-07	S26361-F5315-E*	Added 3.5" SAS 12G SSDs
2014-07-03	S26361-F5243-E170	order code of FBU was wrong (changed from -E125)
2014-07-02	S26361-F2222-E40 / -L40	NVIDIA Tesla K40 added
2014-06-30	S26361-F3301-E123	Added certification for India
2014-06-16	S26361-F3240-xxx	
2014-06-16	S26361-F3239-xxx	
2014-06-16	S26361-F3242-E1 / -L1	
2014-06-10	S26361-F5319-E*	Added 3.5" SATA 6G SSDs
2014-05-19	S26361-F3848-E517	
2014-05-12	sw PAGES 32/64 bit	deleted
2014-05-09	PRIMERGY SX350 S8	Added new base version
2014-05-06	S26361-F5250-E1	Emulex OCe14102 integrated
2014-03-31	2.5" Mod. RAID	many changes, added Cougar 4 (2GB)
2014-04-01	SAS Expander in 2.5"	SAS Expander can be choosen without "upgrade to 24x HDDs" (for pure SAS2.0 configurations only); L-parts corrected & added
2014-03-25	S26361-F1790-L243	added
2014-03-26	S26361-F3713-E3	changed from 1x per system --> 4x per System
2014-03-06	HDD oob monitoring	inserted into System Management products
2014-03-06	PCIe SSD	inserted into section "ext. SAS contr.,"; changed name of folder
2014-02-13	2.5" Mod. RAID	inserted E324 medium cage, updated texts, changed structure
2014-02-10	S26361-F2222-E924	NVIDIA GRID K2 added
2014-01-30	S26361-F5303-*	New SATA SSDs added.
2014-01-30	S26361-F5297-*	New SAS 12G SSDs added.
2014-01-28	all FC controller	max. count changed from 4 to 8
2014-01-21	Cover	Content list corrected
2013-11-29	S26361-F3837-L64	SATA DOM added
2013-12-11	Conf Diagram 2.5"	HDD boxes corrected (PCIe in the medium area), bottom area only SAS2.0 or SAS3.0
2013-12-02	redundant fan kit	2nd CPU requires always a redundant fan kit
2013-10-28		restriction for 2.5" BC-SAS HDD with "F3554-E8" removed.
2013-10-18	SAS Expander	Resourcensteuerung: requires minimum 1x SAS2.0 RAID controller (Cougar 2 or 3)
2013-10-18	PCIe Card lenght	corrected
2013-10-16	S26361-F4610-E2 / -E4	added new 1Gb NICs from Intel
2013-10-11	SAS3.0 Controller	inserted in 2.5"Mod. RAID
2013-10-11	2.5" Mod. RAID	simplified and new structured
2013-10-09	S26113-F615-E10	add comment "110V range not supported", delivery starts Jan 2014
2013-10-08	S26113-F574-E12	corrected: 800W PSU
2013-09-19		Memory hint on CPU page extended
2013-09-13	S26361-F5247-E112	HDD 1.2TB SAS 10K added.
2013-09-01		First release